MULTI LAYER CERAMIC CAPACITORS

- GML SERIES -

DESCRIPTION

- MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.
- CCE GML series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R and X5R are used for this series product.

FEATURES

- Standard size with thin thickness.
- Small size with high capacitance.
- Capacitor with lead-free termination (pure Tin).

APPLICATIONS

- For LCD panels.
- For PCMCA cards.

GML

SERIES

- For IC packaging and modules.
- Any thickness concerned products.



ORDERING INFORMATION



=47x105

 $=4.7 \mu F$

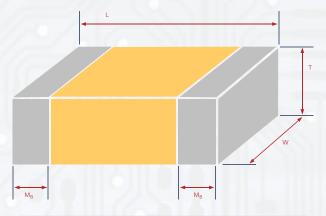
=4,700,000 pF

GENERAL ELECTRICAL DATA

DIELECTRIC	X7R	X5R			
SIZE	0402, 0603, 0805, 1206, 1210				
CAPACITANCE RANGE*	1μF to 10μF	0.22μF to 47μF			
CAPACITANCE TOLERANCE**	K (±10%), M (±20%)				
RATED VOLTAGE	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V			
OPERATING TEMPERATURE	-55 to +125°C	-55 to +85°C			
CAPACITANCE CHARACTERISTIC	±15%				
TERMINATION	Ni / Sn (lead-free termination)				

^{*} Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R. ** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in aml condition for 24±2 hours before measurement





SIZE INCH (MM)	L (MM)	W (MM)	T (MM) SYMBOL		M _B (MM)	
0402 (1005)	1.00 ± 0.2	0.5 ± 0.2	0.30 ± 0.03	L	0.25 ± 0.10	
0603 (1608)	1.6 +15 / -0.10	0.8+ 0.15 / - 0.10	0.50 ± 0.10	Н	0.40 ± 0.15	
0805 (2012)	2.00 ± 0.20	1.25±0.20	0.85 ± 0.10	Т	0.50 ± 0.20	
1206	2.20 . 0.20	1.40 - 0.20	0.85 ± 0.10	Т	0.40 - 0.00	
(3216)	3.20 ± 0.20	1.60 ± 0.20	1.15 ± 0.15	J	0.60 ± 0.20	
1210	3.20 ± 0.30	2.50±0.20	0.85 ± 0.10	Т	0.75 ± 0.25	
(3225)	3.20 ± 0.30	2.50±0.20	2.00 + 0.20	0.75 ± 0.25		

16 VDC

25 VDC 50 VDC

50: 100: 100 VDC





PACKAGING

T: 7" reeled

G: 13" reeled

CAPACITANCE RANGE

- X7R DIELECTRIC

	DIELECT	ΓRIC		X7R									
	SIZE			0805				12	06		1210		
F	RATED VO	LTAGE	10	16	25	50	10	16	25	50	10	16	100
	1.0uF	105											
E E	1.5uF	155								\mathcal{H}			
RANGE	2.2uF	225		Т	Т								K
	3.3uF	335		7/1									
CAPACITANCE	4.7uF	475	Т							14			
PAC	6.8uF	685		16									
S	10uF	106					Т						
	22uF	226											

- X5R DIELECTRIC

	DIELECT	TRIC	_	T		7				1	X	5R		7						
	SIZE		4	0402			0603			08	05				1206				1210	16
	RATED VO	LTAGE	6.3	10	25	6.3	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22uF	224			L		Н	Н												
	0.47uF	474	F	1	L					l.										
111	1.0uF	105	L				н	Н		Т	Т	Т		Т	Т	Т	Т			
CAPACITANCE RANGE	1.5uF	155								Т	Т			Т	Т	Т				
E R/	2.2uF	225	L							Т	Т	Т		Т	Т	Т	Т			
ANC	3.3uF	335												Т	Т	Т		Т		
ACIT	4.7uF	475	L				Н			Т	Т	Т		Т	Т	Т		Т		
CAP,	6.8uF	685																		
	10uF	106				G				Т	Т			J/T		Т		Т		Т
	22uF	226								Т			Т		Т				Т	
	47uF	476											Т							

PACKAGING STYLE AND REEL SIZE

CIZE	THICKNES	S MASS	7" REEL				
SIZE	(MM) / SY	MBOL	PAPER TAPE	PLASTIC TAPE			
0402 (1005)	0.22	F	10k				
0402 (1005)	0.33	L	15k				
0603 (1608)	0.50	g	4k	12/200			
0603 (1608)	0.60	Н	4k	(((,)			
0805 (2012)	0.95	Т	4k	1/2 0			
1207 (2217)	0.95	T	4k				
1206 (3216)	1.30	J		3k			
1210 (2225)	0.95	Т		3k			
1210 (3225)	2.00	K		1k			







RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS	TEST (CONDITION		REQUIR	REMENTS
1.	Visual and Mechanical			- No remarkat		ividual specification sheet.
2.	Capacitance	- Test temp.: Room Tempera		- Shall not exc	ceed the limits giv	ven in the detailed spec.
3.		Cap≤10μF, 1.0±0.2Vrms, 1k Cap>10μF, 0.5±0.2Vrms, 12		X7R / X5R:	RATED VOL.	D.F.
	Q/ D.F.	** Test condition: 0.5±0.2Vr	ms, 1KHz±10%		100V	≤5%
	(Dissipation Factor)	GML10 X5R ≥475(10V), GN	1L04 X5R series		50V, 25V, 16V, 10V	≤10%
	ractory	*Before initial measurement 150°C for 1hr then set for 24	(Class II only): To apply de-aging at		6.3V	≤5%
4.	Dielectric Strength	- To apply voltage: 250% rat - Duration: 1 to 5 sec. - Charge and discharge curr	ed voltage.	- No evidence	of damage or fla	ash over during test.
5.	Insulation Resistance	- Test temp.: Room Tempera - To apply rated voltage for		≥10GΩ or Rx0	C ≥ 100Ω - F whic	chever is smaller.
6.		With no electrical load.			ПУЛ	40000
		T.C.	OPERATING TEMPERATURE		T.C.	CAPACITANCE CHANGE
		X7R	-55~125°C at 25°C		X7R	Within ±15%
		X5R	-55~85°C at 25°C		X5R	Within ±15%
		- Before initial measurement To apply de-aging at 150°C room temp. - Measurement voltage for 0	for 1hr then set for 24± 2 hrs at			
		0402	0603			
			Cap<1µF: 1V			
	Temperature Coefficient	Cap=1µF: 0.5V** 0402 X7R 224-16V: 0.5V 0402 X7R 474-10V: 0.5V 0402 X5R 475M6R3: 0.5	/ 0603 X5R 106-10V: 0.5V			
		1μF <cap<10μf: 0.2v<br="">**0402 X7R 105M6R3V: 0.</cap<10μf:>	2V Cap>4.7μF: 0.2V	1/1		
11		Cap≥10μF: 0.1V				
		0805	1206 / 1210			
			Cap<10µF: 1V			
		Cap=10µF: 0.5V 0805 X7R 475/6.3V~25V: 0	0.5V 10μF <cap≤100μf: 0.5v<="" td=""><td>71</td><td></td><td></td></cap≤100μf:>	71		
		Cap>10μF: 0.2V	Cap>100µF: 0.2V 1206 X5R 107-6.3V: 0.2V			
7.	Adhesive Strength of Termination	- Pressurizing force: 5N (≤ 0 - Test time: 10±1 sec.	603) and 10N (>0603)	- No remarkak	ole damage or re	moval of the terminations.
8.	Vibration Resistance	room temp.	ach in three mutually (Class II only): for 1hr then set for 24± 2 hrs at to be made after de-aging at	- No remarkak - Cap change	ole damage. and Q/D.F.: To m	neet initial spec.
9.	Solderability	- Solder temperature: 235±5 - Dipping time: 2±0.5 sec.	5°C	- 95% min. co	verage of all met	alized area.
10.	Bending Test	1 mm per second until the countries the pressure shall be maintal - Before initial measurement To apply de-aging at 150°C room temp.	pressurizing rod at a rate of about leflection becomes 1 mm and then ined for 5±1 sec.	(This ca capacita	: X7R/X5R: within pacitance change ance underspecif	±12.5% e means the change of ied flexure of substrate asured before the test.)







RELIABILITY TEST CONDITIONS AND REQUIREMENTS

		REQUIREMENTS				
Resistance to Soldering Heat	- Solder temperature: 260±5°C - Dipping time: 10±1 sec - Preheating: 120 to 150°C for 1 minute before imme rse the capacitor in a eutectic solder Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	- No remarkable damage Cap change: X7R/X5R: within ±7.5% - Q/D.F., I.R. and dielectric strength: To meet initial requirements 25% max. leaching on each edge.				
	- Conduct the five cycles according to the temperatures and time. STEP TEMP. (°C) TIME (MIN) 1 Min. operating temp. +0/-3 30±3					
	2 Room Temp 2~3	- No remarkable damage.	7.50			
Temperature Cycle	3 Max. operating temp. +3/-0 30±3	- Cap change: X/R/X5R: within : - Q/D.F., I.R. and dielectric stren	±7.5% ngth: To meet initial			
	4 Room Temp 2~3	requirements.				
	- Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.					
	- Test temp.: 40±2°C	- No remarkable damage. - Cap change: X7R/X5R: within - Q/D.F. value: X7R/X5R:	±25%			
Humidity (Damp Heat) Steady State	- Humidity: 90~95% RH	RATED VOL.	D.F.			
	- Test time: 500+24/-0hrs. - Before initial measurement (Class II only): To apply de-aging	100V	≤7.5%			
	at 150°C for 1hr then set for 24±2 hrs at room temp.	25V, 16V	≤15%			
	at 150°C for 1hr then set for 24±2 hrs at room temp.	10V	≤20%			
		50V, 6.3V	≤30%			
		- I.R.: 1G Ω or RxC≥10 Ω -F whi	chever is smaller.			
	- Test temp.: 40±2°C - Humidity: 90~95%RH - Test time: 500+24/-0 hrs To apply voltage: Rated voltage.	No remarkable damage. *Cap change: X7R/X5R: within ±25% *Q/D.F. value: X7R/X5R:				
Humidity	at 150°C for 1hr then set for 24±2 hrs at room temp.	RATED VOL.	D.F.			
(Damp Heat)	- Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	100V	≤7.5%			
Load	at 155 6 for the dien set for 2422 his at 166m temp.	25V, 16V	≤15%			
		10V	≤20%			
		50V, 6.3V	≤30%			
		- I.R.: 500MΩ or RxC≥5 Ω-F whichever is smaller.				
	- Test temp.: X7R: 125±3°C X5R: 85±3°C - Test time: 1000+24/-0 hrs. - To apply voltage: 150% of rated voltage. **100% of rated voltage for below range.	- No remarkable damage. - Cap change: X7R/X5R: within ±25% - Q/D.F. value: X7R/X5R:				
10.1	RATED CAPACITANIE	RATED VOL.	D.F.			
High Temperature	SIZE DIELECTRIC VOLTAGE RANGE	100V	≤7.5%			
Load	GML04 X5R 6.3V C ≥ 1.0 μF	25V, 16V	≤15%			
(Litualance)	GML21 X5R X7R X6S ≤10V C ≥ 10 μF	10V	≤20%			
	- Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp . * - Cap. / DF(Q) / I.R. Measurement to ©r de-aging at 150°C		≤30% never is smaller.			
	Temperature Cycle Humidity (Damp Heat) Steady State Humidity (Damp Heat) Load	Resistance to Soldering Heat - Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. - Cap. / DF(Q) / LR. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. - Conduct the five cycles according to the temperatures and time. Temperature Cycle	Resistance to Soldering Heat - Referential measurement (Class II only): To apply de-aging at 150°C for Ir then set for 24±2 hrs at room temp. - Cap. / DT(Q) / IR. Measurement to be made after de-aging at 150°C for Ir then set for 24±2 hrs at room temp. - Conduct the five cycles according to the temperatures and time. Temperature			

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



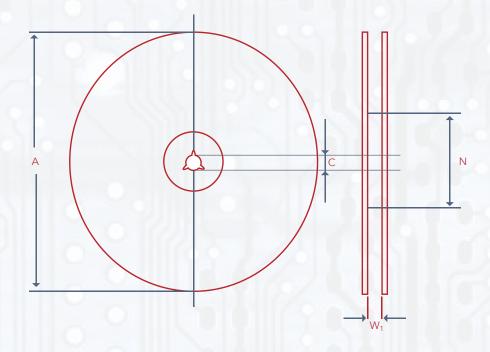




RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS		TEST CO	ONDITION	<i>\\</i>	REQUIF	REQUIREMENTS		
		- Test time - To apply	p.: X7R: 125±3°C X :: 1000+24/-0 hrs. voltage: 150% of ra rated voltage for be	ted voltage.		- No remarkable damage. - Cap change: X7R/X5R: within ±25% - Q/D.F. value: X7R/X5R:			
	High	SIZE	DIELECTRIC	RATED	CAPACITANE	RATED VOL.	D.F.		
4.5	Temperature	9		VOLTAGE	RANGE	_ 100V	≤7.5%		
15.	Load	GML04	X5R	6.3V	C ≥ 1.0 µF	25V, 16V	≤15%		
	(Endurance)	GML21	X5R I X7R	≤10V	C ≥ 10 µF		≤20%		
		at 150°C fe	itial measurement (Cor 1hr then set for 24 DF(Q) / I.R. Measure	4±2 hrs at room	50V, 6.3V	≤30%			
			n set for 24±2 hrs at		ignig at 150 C	- I.R.: 1GΩ or RxC≥10Ω-F whichever is smaller.			

TAPE AND REEL DIMENSION



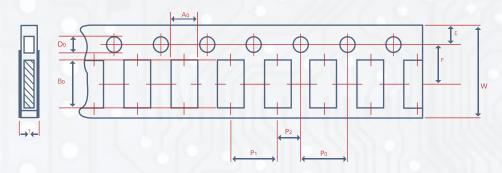
SIZE		0402, 0603, 0805, 1206, 1210	
REEL SIZE	7"	10"	13"
С	13.0±0.5	13.0±0.5	13.0±0.5
W ₁	10.0±1.5	10.0±1.5	10.0±1.5
А	178.0±2.0	250.0±2.0	330.0±2.0
N	60.0+1.0/-0	50 min	50 min



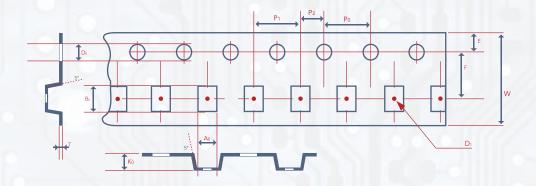


TAPE AND REEL DIMENSIONS

-The dimension of paper tape



-The dimension of plastic tape

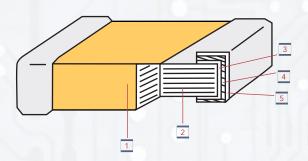


SIZE	0402	0603	0805	12	206	12	210
THICKNESS	L	Н	Т	Т	J	Т	К
A ₀	0.70 ± 0.20	1.05 ± 0.30	1.50 ± 0.20	1.90 ± 0.50	<2.00	<3.05	<3.05
B ₀	1.20 ± 0.20	1.80 ± 0.30	2.30 ± 0.20	3.50 ± 0.50	<3.70	<3.80	<3.80
Т	≤0.80	≤1.20	≤1.20	≤1.20	0.23 ± 0.1	0.23 ± 0.1	0.23 ± 0.1
K ₀		1 - 16	7.1-17		<2.00	<1.50	<2.50
W	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30
P ₀	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
10XP ₀	40.00 ± 0.10	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20
P ₁	2.00 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
P ₂	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05
D_0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0
D ₁		1.7	-	-	1.00 ± 0.10	1.00 ± 0.10	1.00 ± 0.10
E	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
F	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05





CONSTRUCTIONS



NO.	N/	X7R, X5R		
1	Cerami	BaTiO ₃ based		
2	Inner E	Inner Electrode		
3	Inner Layer		Cu	
4	Termination	Middle Layer	Ni	
5		Outer Layer	Sn (Matt)	

STORAGE AND HANDLING CONDITIONS

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

RECOMMENDED SOLDERING CONDITIONS

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N2 within oven are recommended.

